



Final Product Change Notification **Update**

202204008F01U01 : LPC82x LPC83x Revision Change to 1B

Note: This notice is NXP Company Proprietary.

Issue Date: May 13, 2022 **Effective date:** Aug 11, 2022

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Management summary

Microcontroller products LPC82x and LPC83x will be sourced from the new product revision "1B" to resolve the BOD.1 errata.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input checked="" type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

Microcontroller products LPC82x and LPC83x will be sourced from the new product revision "1B".

- This design change fixes the BOD.1 errata as documented in the device errata sheet updates.

- The following errata sheets have been updated with the BOD.1 errata:

LPC82x errata sheet has been updated to rev 1.4, https://www.nxp.com/docs/en/errata/ES_LPC82X.pdf

LPC83x errata sheet has been updated to rev 1.2, https://www.nxp.com/docs/en/errata/ES_LPC83X.pdf

- The design change has no reliability impact.

Reason

- To fix the BOD.1 functional deviation as documented in the errata sheets.

Identification of Affected Products

Top Side Marking

The last character of the last line of the device top side marking changes from "A" to "B"

Product Availability

Sample Information

Samples are available from May 11, 2022

Production

Planned first shipment Aug 04, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

The design changed resolved the BOD.1 errata described in the errata sheets.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jun 12, 2022.

Update Information

PCN version F01 had the incorrect self qualification report attached. Update U01 has the correct self qualification report.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Quality Manager
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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	New Orderable Part#	12NC New	Product Type New	Product Description New	Product Line	Notes
LPC822M101JDH20J	93530400 5118	LPC822M101J DH20	32-bit ARM M0+	(T)SSOP20	SOT360-1	RFS	No					BLM1	
LPC824M201JDH20J	93530400 6118	LPC824M201J DH20	32-bit ARM M0+	(T)SSOP20	SOT360-1	RFS	No					BLM1	
LPC822M101JHI33Y	93530400 7518	LPC822M101J HI33	32-bit ARM M0+	H(V)QFN32W F	SOT617-3	RFS	No					BLM1	
LPC822M101JHI33E	93530400 7551	LPC822M101J HI33	32-bit ARM M0+	H(V)QFN32W F	SOT617-3	RFS	No					BLM1	
LPC822M101JHI33K	93530400 7557	LPC822M101J HI33	32-bit ARM M0+	H(V)QFN32W F	SOT617-3	RFS	No					BLM1	

